

N-channel 60 V, 0.012 Ω typ., 15 A STripFET™ F7 Power MOSFET in a DPAK package

Datasheet - production data

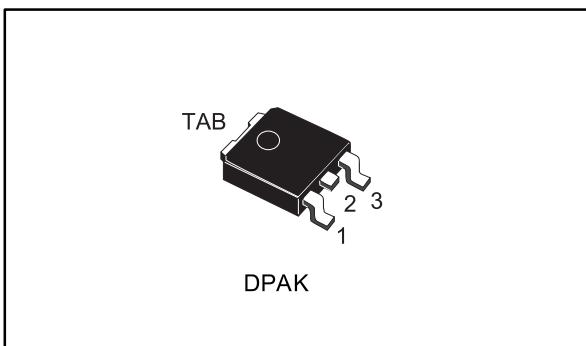
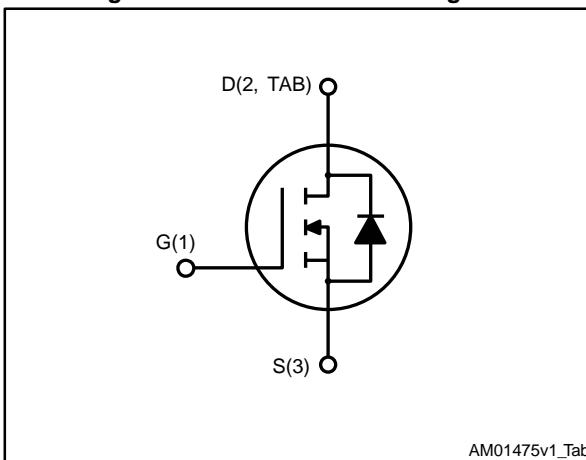


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max.	I _D
STD46N6F7	60 V	0.014 Ω	15 A

- Among the lowest R_{DS(on)} on the market
- Excellent figure of merit (FoM)
- Low C_{rss}/C_{iss} ratio for EMI immunity
- High avalanche ruggedness

Applications

- Switching applications

Description

This N-channel Power MOSFET utilizes STripFET™ F7 technology with an enhanced trench gate structure that results in very low on-state resistance, while also reducing internal capacitance and gate charge for faster and more efficient switching.

Table 1: Device summary

Order code	Marking	Package	Packaging
STD46N6F7	46N6F7	DPAK	Tape and reel

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1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	60	V
V_{GS}	Gate-source voltage	± 20	V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25^\circ\text{C}$	15	A
$I_D^{(1)}$	Drain current (continuous) at $T_C = 100^\circ\text{C}$	15	A
$I_{DM}^{(1)(2)}$	Drain current (pulsed)	60	A
$P_{TOT}^{(1)}$	Total dissipation at $T_C = 25^\circ\text{C}$	60	W
T_j	Operating junction temperature range	-55 to 175	$^\circ\text{C}$
T_{stg}	Storage temperature range		

Notes:(1)This value is limited by package and rated according to R_{thj-c}

(2)Pulse width limited by safe operating area

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb max.	50	$^\circ\text{C/W}$
$R_{thj-case}$	Thermal resistance junction-case max.	2.5	$^\circ\text{C/W}$

Notes:(1)When mounted on FR-4 board of 1 inch², 2oz Cu, t < 10 sec

2 Electrical characteristics

($T_C = 25^\circ\text{C}$ unless otherwise specified)

Table 4: On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$	60			V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}$ $V_{DS} = 60 \text{ V}$			1	μA
I_{GSS}	Gate-body leakage current	$V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2		4	V
$R_{DS(\text{on})}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 7.5 \text{ A}$		0.012	0.014	Ω

Table 5: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 30 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$	-	1035	-	pF
C_{oss}	Output capacitance		-	450	-	pF
C_{rss}	Reverse transfer capacitance		-	53	-	pF
Q_g	Total gate charge	$V_{DD} = 30 \text{ V}, I_D = 15 \text{ A}, V_{GS} = 10 \text{ V}$ (see Figure 14: "Test circuit for gate charge behavior")	-	17	-	nC
Q_{gs}	Gate-source charge		-	5.7	-	nC
Q_{gd}	Gate-drain charge		-	5.7	-	nC

Table 6: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 30 \text{ V}, I_D = 7.5 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$ (see Figure 13: "Test circuit for resistive load switching times")	-	14.5	-	ns
t_r	Rise time		-	15.3	-	ns
$t_{d(off)}$	Turn-off delay time		-	19.4	-	ns
t_f	Fall time		-	8	-	ns

Table 7: Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{SD(1)}$	Forward on voltage	$I_{SD} = 15 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.2	V
t_{rr}	Reverse recovery time	$I_D = 15 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 48 \text{ V}$ (see Figure 15: "Test circuit for inductive load switching and diode recovery times")	-	26.8		ns
Q_{rr}	Reverse recovery charge		-	14.2		nC
I_{RRM}	Reverse recovery current		-	1.06		A

Notes:

⁽¹⁾Pulsed: pulse duration = 300 μs , duty cycle 1.5%

2.1

Electrical characteristics (curves)

Figure 2: Safe operating area

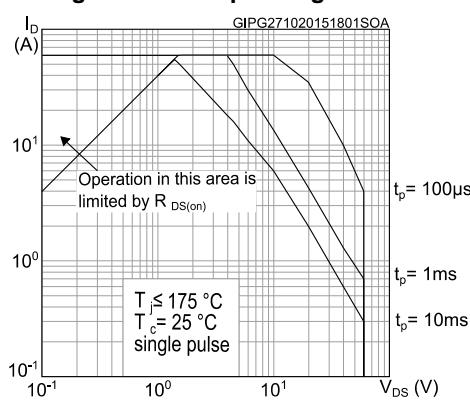


Figure 3: Thermal impedance

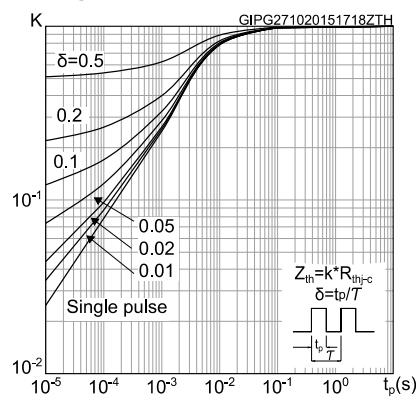


Figure 4: Output characteristics

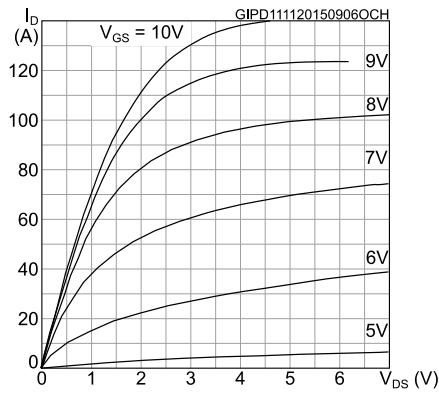


Figure 5: Transfer characteristics

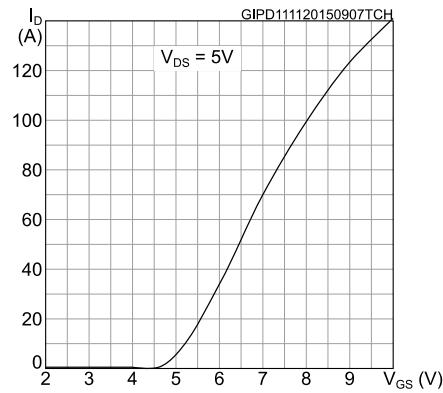


Figure 6: Gate charge vs gate-source voltage

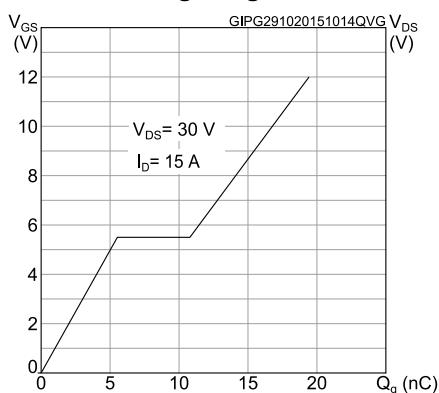


Figure 7: Static drain-source on-resistance

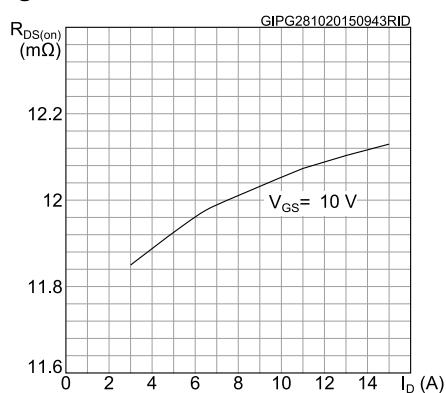
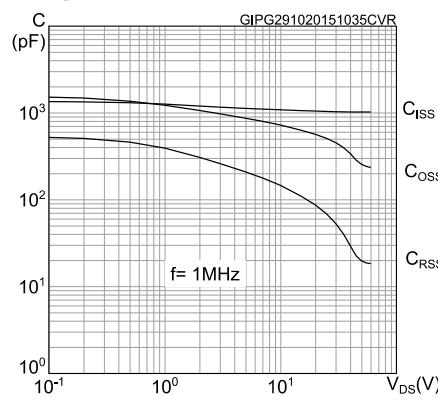
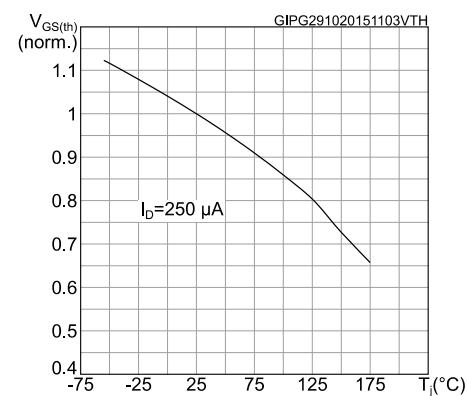
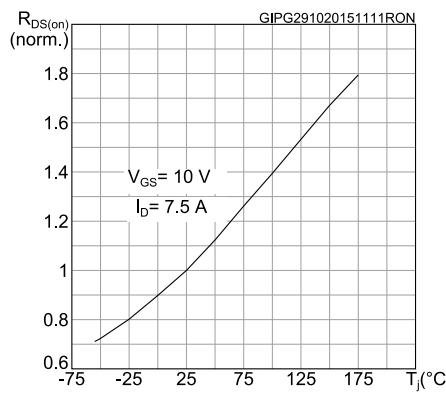
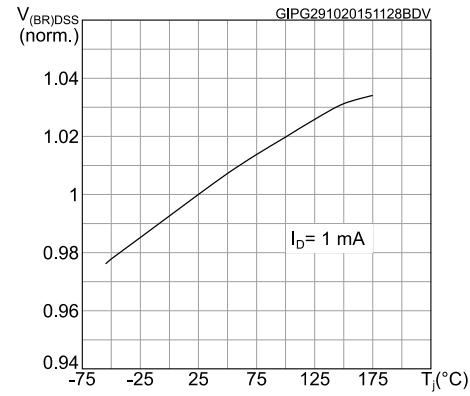
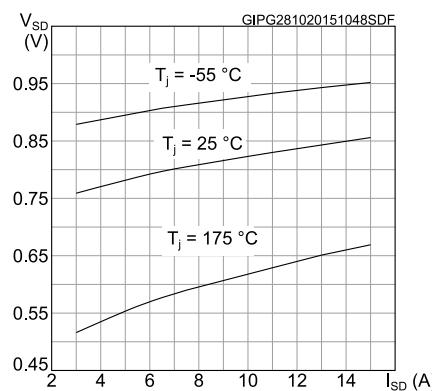


Figure 8: Capacitance variations**Figure 9: Normalized gate threshold voltage vs temperature****Figure 10: Normalized on-resistance vs temperature****Figure 11: Normalized V(BR)DSS vs temperature****Figure 12: Source-drain diode forward characteristics**

3 Test circuits

Figure 13: Test circuit for resistive load switching times

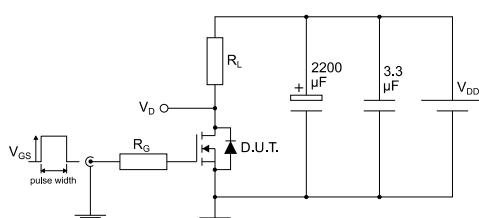


Figure 14: Test circuit for gate charge behavior

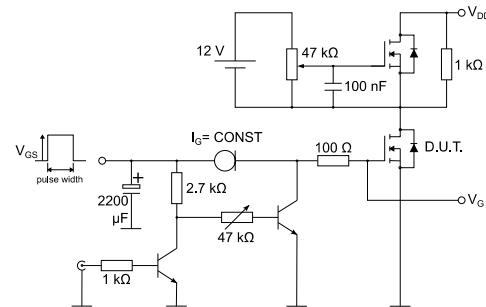


Figure 15: Test circuit for inductive load switching and diode recovery times

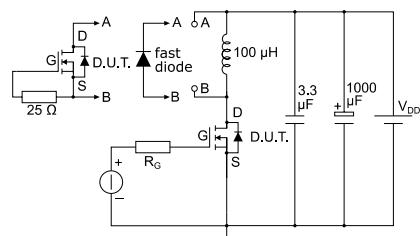


Figure 16: Unclamped inductive load test circuit

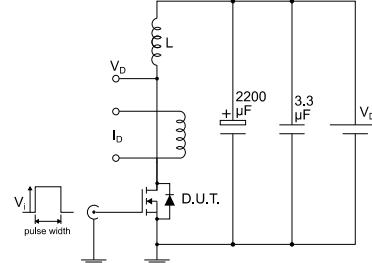


Figure 17: Unclamped inductive waveform

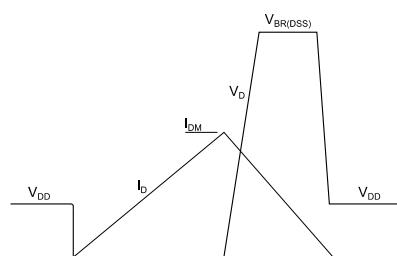
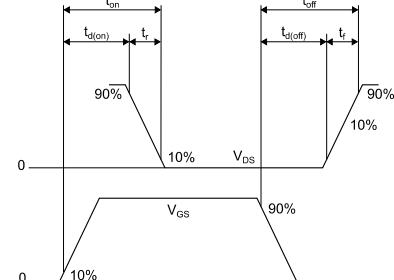


Figure 18: Switching time waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com.
ECOPACK® is an ST trademark.

4.1 DPAK(TO-252) type A package information

Figure 19: DPAK (TO-252) type A package outline

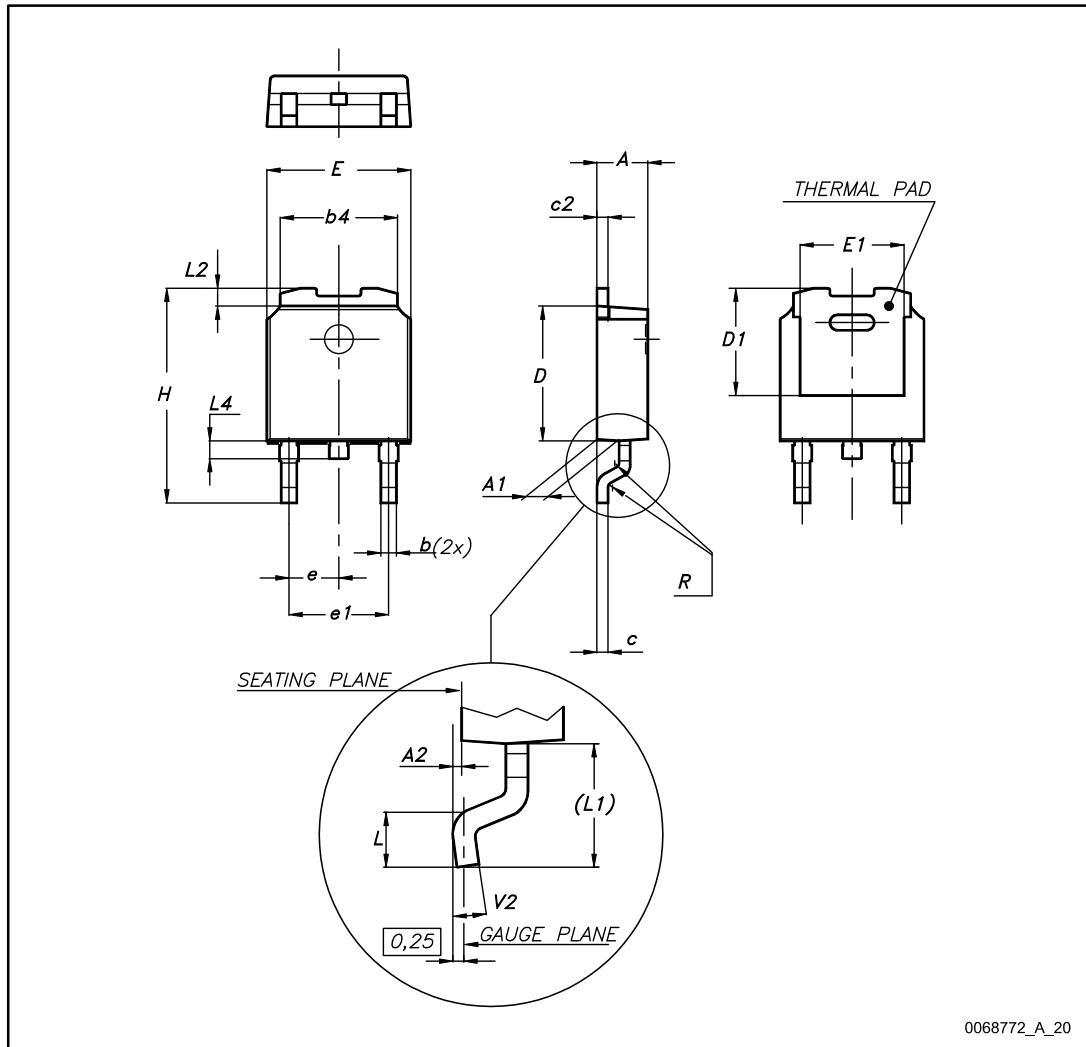
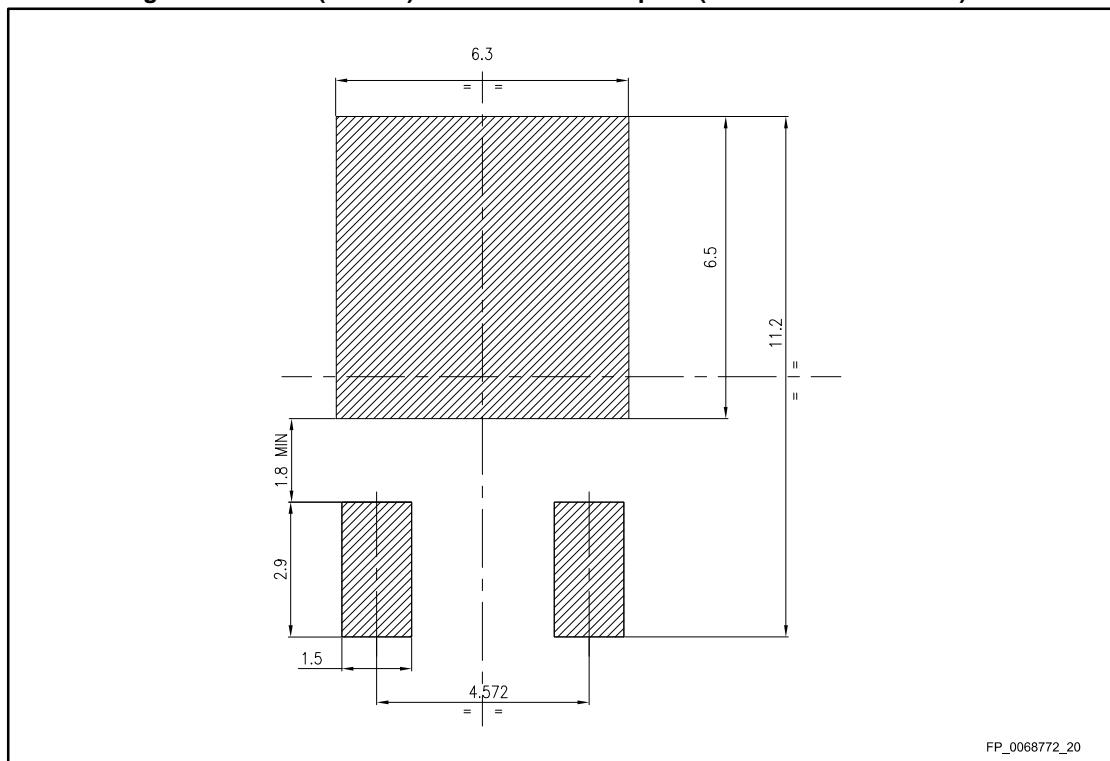


Table 8: DPAK (TO-252) type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	4.60	4.70	4.80
e	2.16	2.28	2.40
e1	4.40		4.60
H	9.35		10.10
L	1.00		1.50
(L1)	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

Figure 20: DPAK (TO-252) recommended footprint (dimensions are in mm)



4.2 Packing information

Figure 21: DPAK (TO-252) tape outline

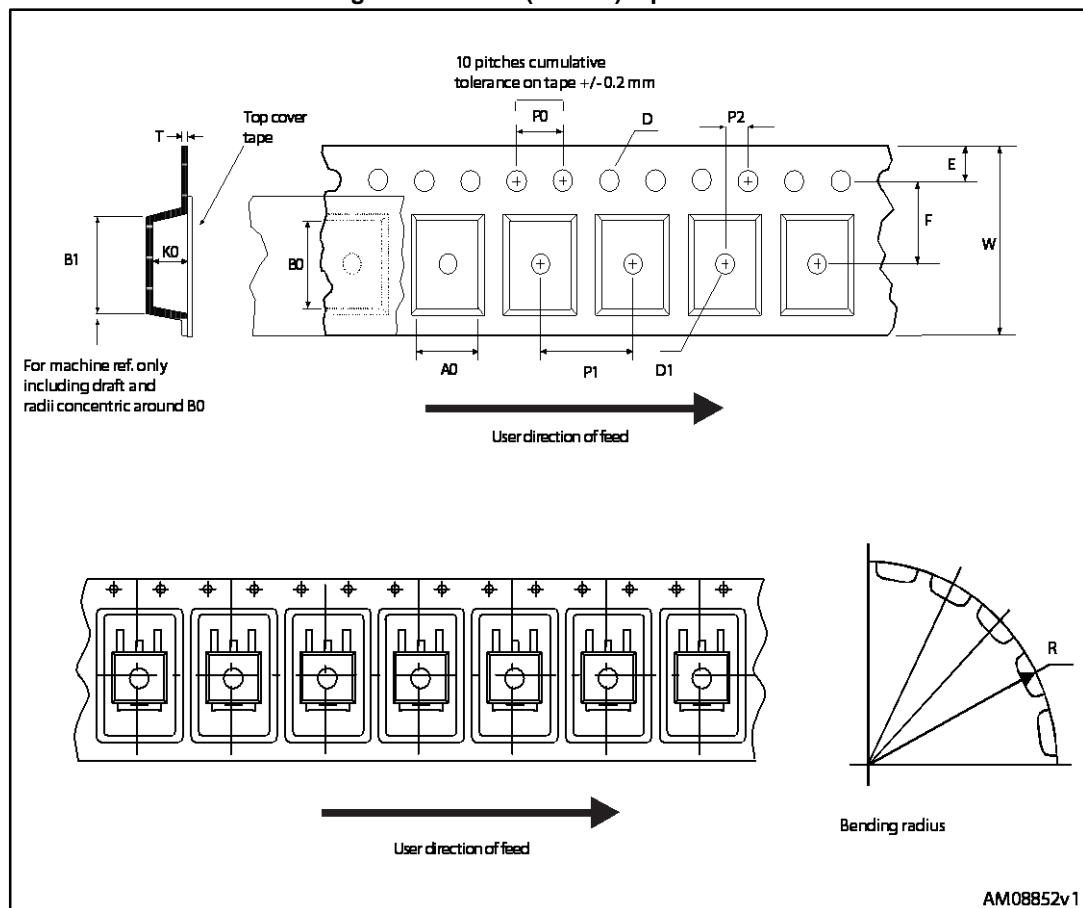


Figure 22: DPAK (TO-252) reel outline

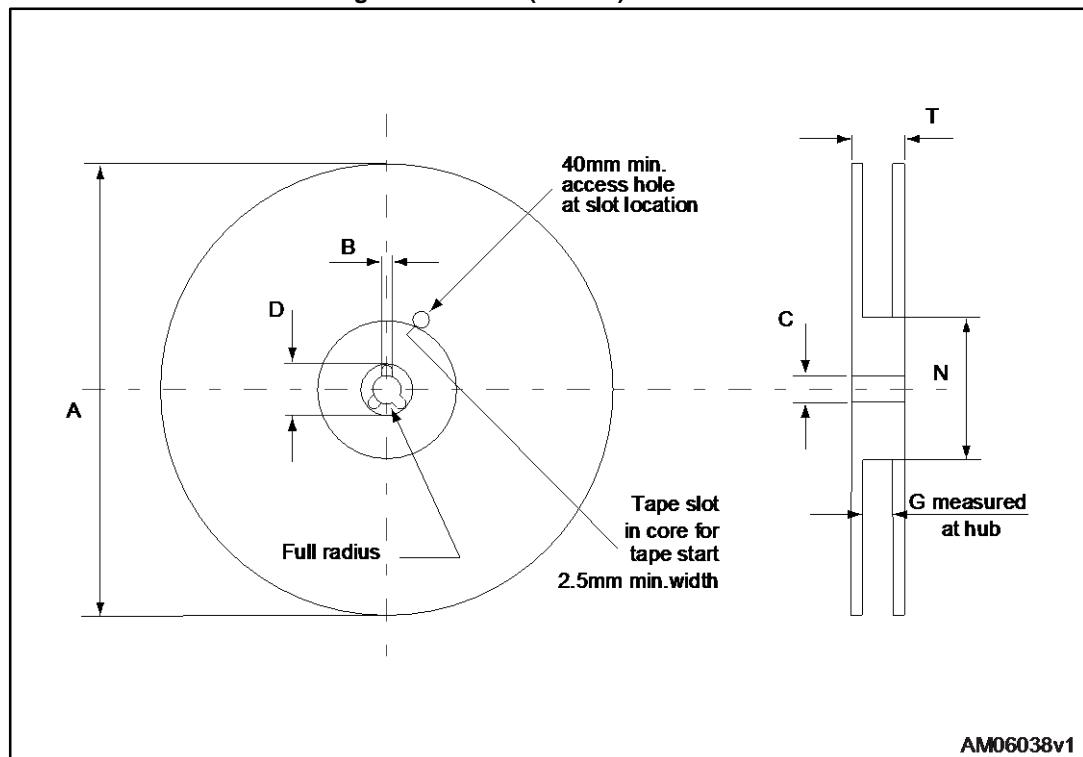


Table 9: DPAK (TO-252) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

5 Revision history

Table 10: Document revision history

Date	Revision	Changes
16-Dec-2015	1	First release.
26-Jan-2016	2	Document status promoted from preliminary to production data.

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